



IECQ Certificate of Conformity

Capability

IECQ Certificate No.:	IECQ-C BSI 14.0052	Issue No.:	5	Status:	Current
Supersedes:	IECQ-C BSI 14.0052 Issue 4	Issue Date:	2023/11/21	Org Issue:	2009/05/13
CB Reference No.:	029/ICA Issue 6	Expiration:	2026/11/30		

Express Circuits Limited
Units 21- 22, Roman Way
Coleshill Industrial Estate, Coleshill
Birmingham, B46 1HQ
United Kingdom

The organization has developed and implemented procedures and related processes which have been assessed by the IECQ Certification Body issuing this certificate and found to comply with the applicable requirements of the IECQ Approved Component Scheme "Capability Certification" which is in accordance with the Basic Rules IECQ 01 "Rules of Procedure", IECQ 03-1 "IECQ General Requirements for all Schemes" and IECQ 03-3 Annex D "IECQ Approved Components Scheme" of the IEC Quality Assessment System for Electronic Component (IECQ), and in respect of standard(s) or specification(s):

- IPC-6011 {July 1996} Generic Performance Specification for Printed Boards
- IPC-6012E {March 2020} Qualification and Performance Specification for Rigid Printed Boards

Process Manual Reference: **EXP-CM-03 Issue 4**

Details of Components/Assemblies/Materials:

Manufacture of rigid printed boards:

- Multilayer boards with Blind and/or buried vias
- Multilayer boards without blind or buried vias
 - Double-sided boards
 - Single sided boards

-- Attached Schedule: 029_ICA Issue 5 Scope.pdf --

Issued by the Certification Body (CB): BSI

Kitemark Court, Davy Avenue
Knowlhill, Milton Keynes MK5 8PP
United Kingdom

Authorized person:
Shahm Barhom



The validity of this certificate is maintained through on-going surveillance audits by the IECQ CB issuing this certificate.

This Certificate of Conformity may be suspended or withdrawn in accordance with the Rules of Procedure of the IECQ System and its Schemes.

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Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 14.0052

CB Certificate No.: 029/ICA

Schedule Number: IECQ-C BSI 14.0052-S

Rev No.: 5

Revision Date: 2023/11/21

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Test Reports:

7293042	4 March 2009
38590	25 March 2009
8011	27 Sept 2021

Board Types Multilayer boards with blind and/or buried vias (Type 4) IPC 6012E Class 3
Multilayer boards without blind or buried vias (Type 3)
Double-sided boards (Type 2)
Single-sided boards (Type 1)

Base Materials: Epoxide woven glass IPC 4101/26
(21, 24, 98, 99, 101, 126)

Board Size: 405 mm x 280 mm (Type 3 & 4)
500 mm x 360 mm (Type 1 & 2)

Conductors: Minimum width: 0.1 mm ± 0.05mm 12 µm foil
Minimum spacing: 0.1 mm ± 0.05mm 18 µm foil

Number of Layers: 16 (Class 2), 12 (Class 3) Maximum

Plated-through hole Diameter: 0.5 mm minimum drilled

Aspect Ratio: 6.4 : 1 (Class 2), 4.6 : 1 (Class 3) Maximum

Finishes: 63:37 Sn/Pb Hot Air Solder Level
Electroless Nickel / Immersion Gold
Electrolytic Nickel and Gold
Organic Solderability Preservative
Immersion Silver
Photoimageable solder resist
IR Cured Notation Ink

Additional: Bonded Heatplanes: Anodized Aluminium
Nickel Plated Copper

Note: It may not be possible to achieve the limits of the capability in combination. Such combinations are determined by the agreed customer detail specification for the PCB ordered.

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BSI, Kitemark Court Davy Avenue Knowlhill Milton Keynes MK5 8PP UK

